

Complementary Darlington Power Transistors

DPAK For Surface Mount Applications

MJD112 (NPN), MJD117 (PNP)

Designed for general purpose power and switching such as output or driver stages in applications such as switching regulators, converters, and power amplifiers.

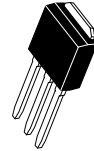
Features

- Lead Formed for Surface Mount Applications in Plastic Sleeves (No Suffix)
- Straight Lead Version in Plastic Sleeves ("-1" Suffix)
- Electrically Similar to Popular TIP31 and TIP32 Series
- NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant*

SILICON
POWER TRANSISTORS
2 AMPERES
100 VOLTS, 20 WATTS

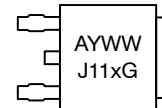


DPAK
CASE 369C

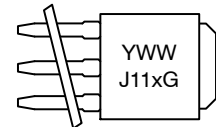


DPAK-3
CASE 369D

MARKING DIAGRAMS



DPAK



DPAK-3

A = Assembly Location
Y = Year
WW = Work Week
x = 2 or 7
G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 8 of this data sheet.

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MJD112 (NPN), MJD117 (PNP)

MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Collector–Emitter Voltage	V_{CEO}	100	Vdc
Collector–Base Voltage	V_{CB}	100	Vdc
Emitter–Base Voltage	V_{EB}	5	Vdc
Collector Current Continuous Peak	I_C	2 4	Adc
Base Current	I_B	50	mAdc
Total Power Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D	20 0.16	W W/ $^\circ\text{C}$
Total Power Dissipation (Note1) @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	1.75 0.014	W W/ $^\circ\text{C}$
Operating and Storage Junction Temperature Range	T_J, T_{stg}	–65 to +150	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction–to–Case	$R_{\theta JC}$	6.25	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction–to–Ambient (Note 1)	$R_{\theta JA}$	71.4	$^\circ\text{C}/\text{W}$

1. These ratings are applicable when surface mounted on the minimum pad sizes recommended.



MJD112 (NPN), MJD117 (PNP)

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector-Emitter Sustaining Voltage (Note 2) ($I_C = 30\text{ mA}$, $I_B = 0$)	$V_{CE(sus)}$	100	–	Vdc
Collector Cutoff Current ($V_{CE} = 50\text{ Vdc}$, $I_B = 0$)	I_{CEO}	–	20	μA
Collector Cutoff Current ($V_{CB} = 100\text{ Vdc}$, $I_E = 0$)	I_{CBO}	–	20	μA
Emitter Cutoff Current ($V_{BE} = 5\text{ Vdc}$, $I_C = 0$)	I_{EBO}	–	2	mA
Collector-Cutoff Current ($V_{CB} = 80\text{ Vdc}$, $I_E = 0$)	I_{CBO}	–	10	μA
Emitter-Cutoff Current ($V_{BE} = 5\text{ Vdc}$, $I_C = 0$)	I_{EBO}	–	2	mA
ON CHARACTERISTICS				
DC Current Gain ($I_C = 0.5\text{ A}$, $V_{CE} = 3\text{ Vdc}$) ($I_C = 2\text{ A}$, $V_{CE} = 3\text{ Vdc}$) ($I_C = 4\text{ A}$, $V_{CE} = 3\text{ Vdc}$)	h_{FE}	500 1000 200	– 12,000 –	–
Collector-Emitter Saturation Voltage ($I_C = 2\text{ A}$, $I_B = 8\text{ mA}$) ($I_C = 4\text{ A}$, $I_B = 40\text{ mA}$)	$V_{CE(sat)}$	– –	2 3	Vdc
Base-Emitter Saturation Voltage ($I_C = 4\text{ A}$, $I_B = 40\text{ mA}$)	$V_{BE(sat)}$	–	4	Vdc
Base-Emitter On Voltage ($I_C = 2\text{ A}$, $V_{CE} = 3\text{ Vdc}$)	$V_{BE(on)}$	–	2.8	Vdc
DYNAMIC CHARACTERISTICS				
Current-Gain – Bandwidth Product ($I_C = 0.75\text{ A}$, $V_{CE} = 10\text{ Vdc}$, $f = 1\text{ MHz}$)	f_T	25	–	MHz
Output Capacitance ($V_{CB} = 10\text{ Vdc}$, $I_E = 0$, $f = 0.1\text{ MHz}$) MJD117, NJVMJD117T4G MJD112, NJVMJD112G, NJVMJD112T4G	C_{ob}	– –	200 100	pF

2. Pulse Test: Pulse Width $\leq 300\text{ }\mu\text{s}$, Duty Cycle $\leq 2\%$.

*These ratings are applicable when surface mounted on the minimum pad sizes recommended.

MJD112 (NPN), MJD117 (PNP)

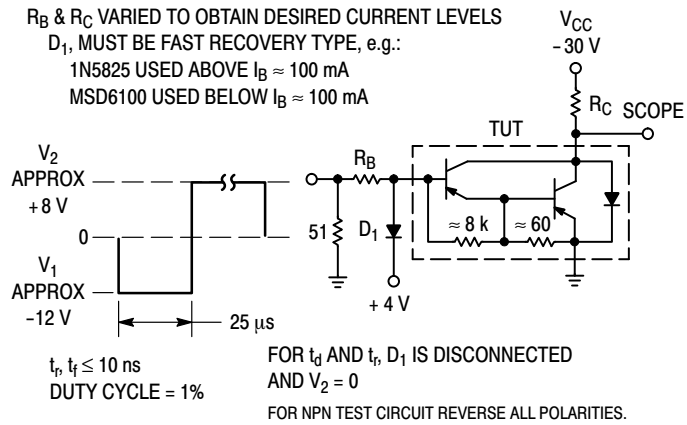


Figure 1. Switching Times Test Circuit

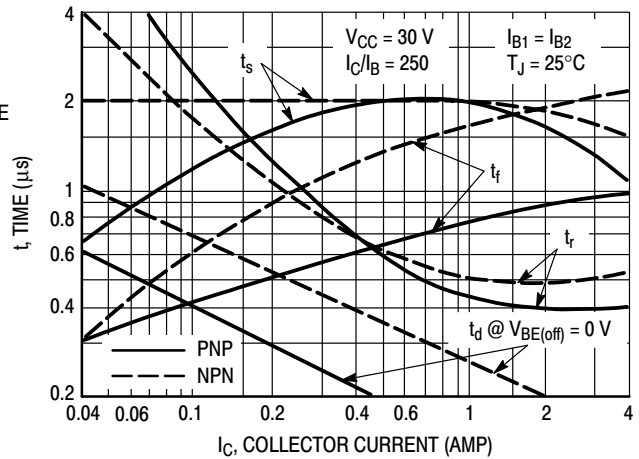


Figure 2. Switching Times

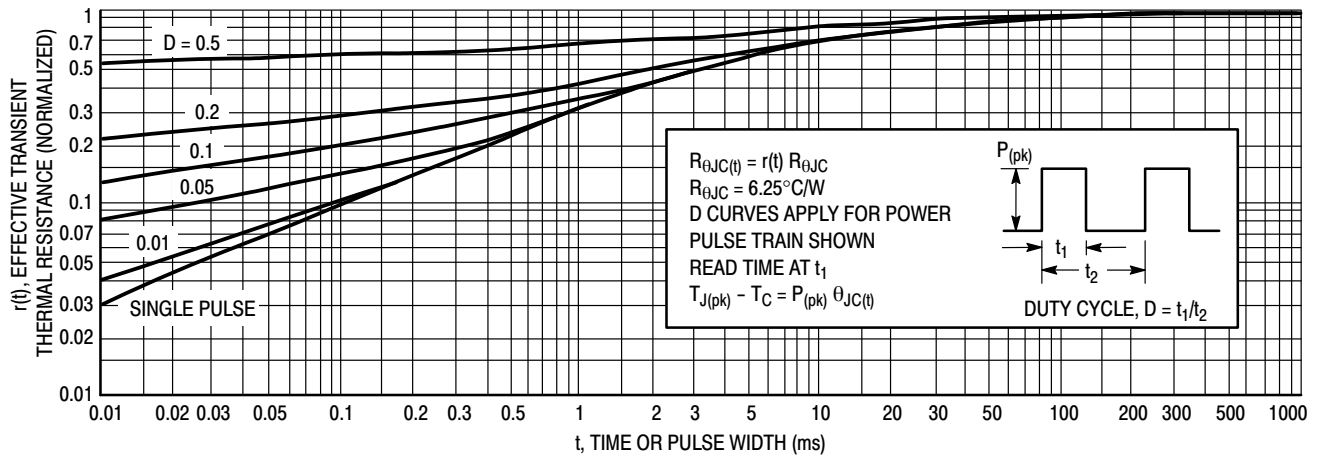


Figure 3. Thermal Response

MJD112 (NPN), MJD117 (PNP)

ACTIVE-REGION SAFE-OPERATING AREA

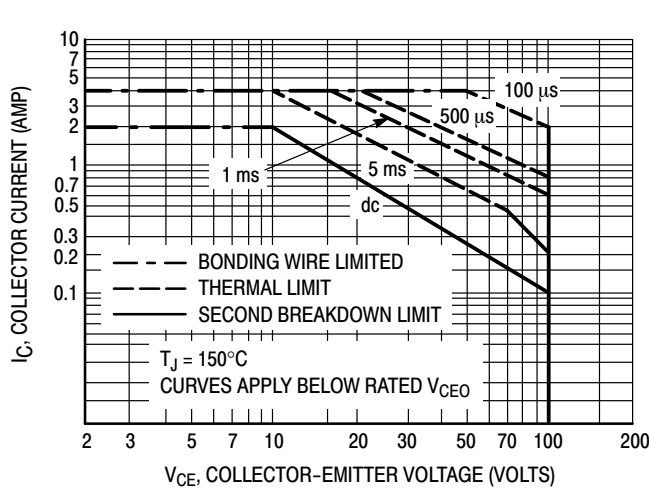


Figure 4. Maximum Rated Forward Biased Safe Operating Area

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figures 5 and 6 is based on $T_{J(pk)} = 150^\circ\text{C}$; T_C is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided $T_{J(pk)} < 150^\circ\text{C}$. $T_{J(pk)}$ may be calculated from the data in Figure 4. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

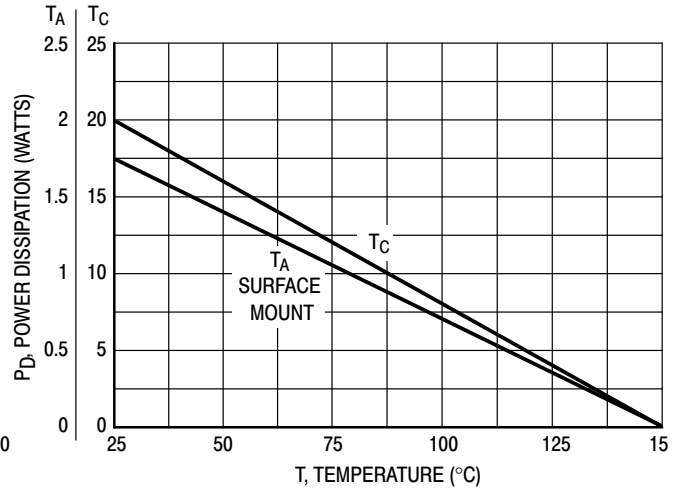


Figure 5. Power Derating

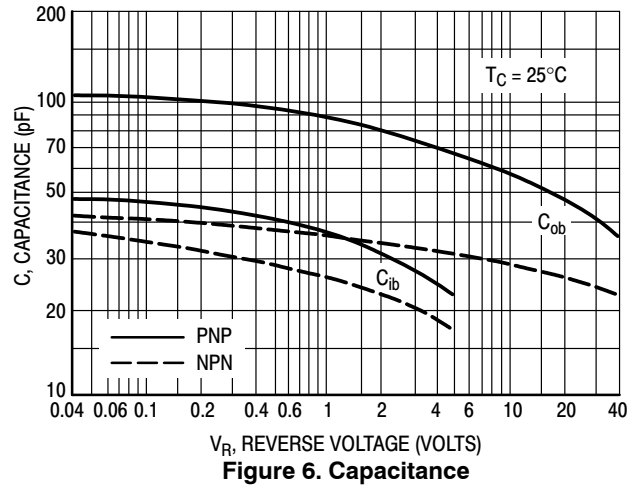
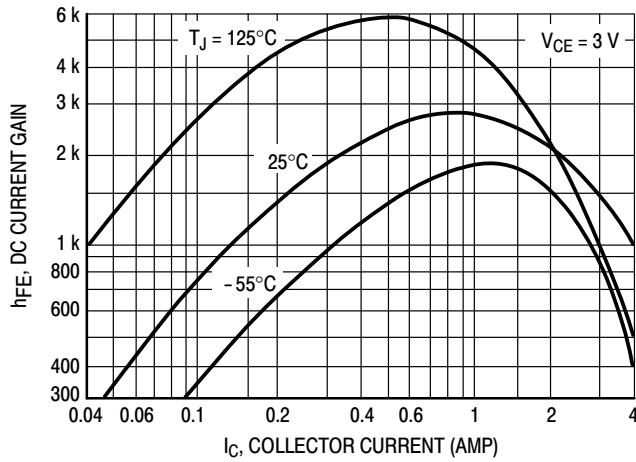


Figure 6. Capacitance

MJD112 (NPN), MJD117 (PNP)

TYPICAL ELECTRICAL CHARACTERISTICS

NPN MJD112



PNP MJD117

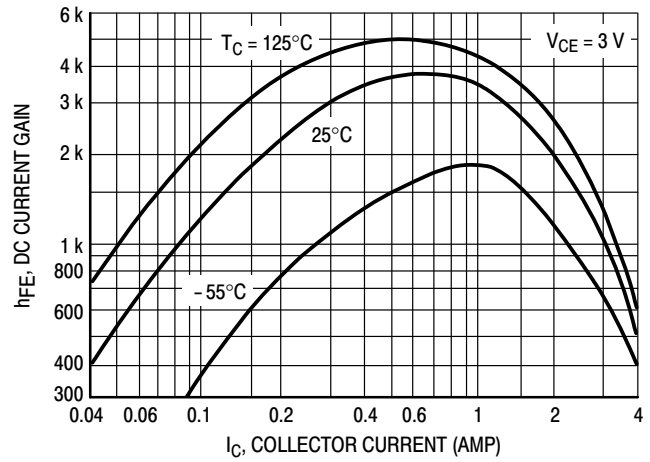


Figure 7. DC Current Gain

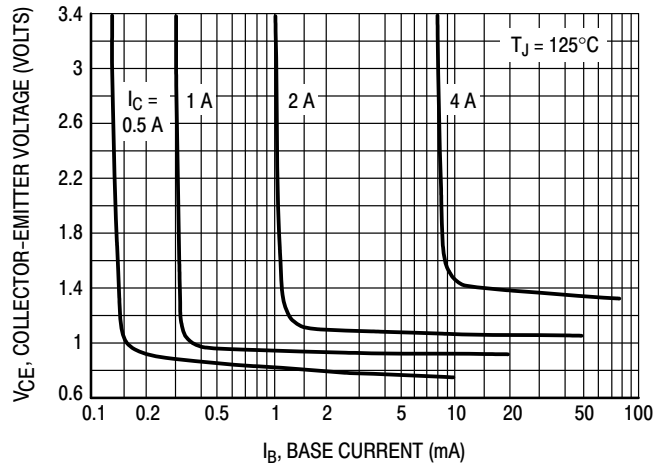
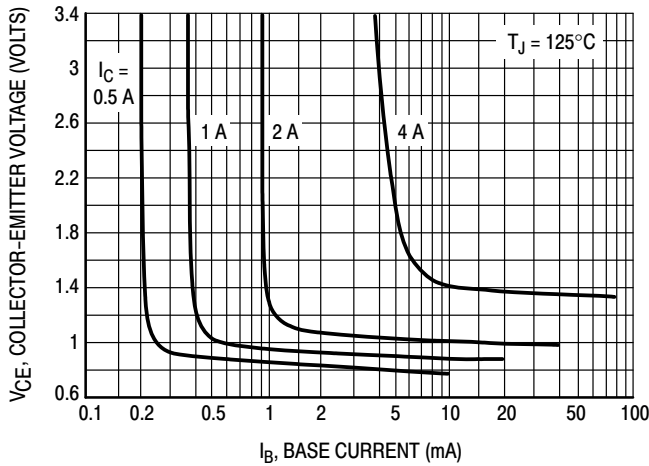


Figure 8. Collector Saturation Region

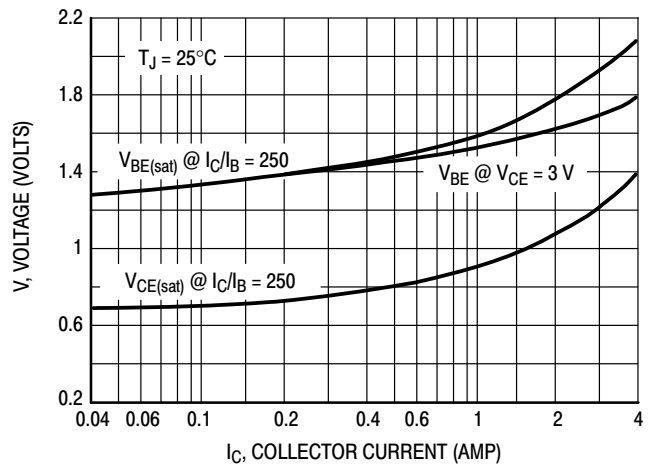
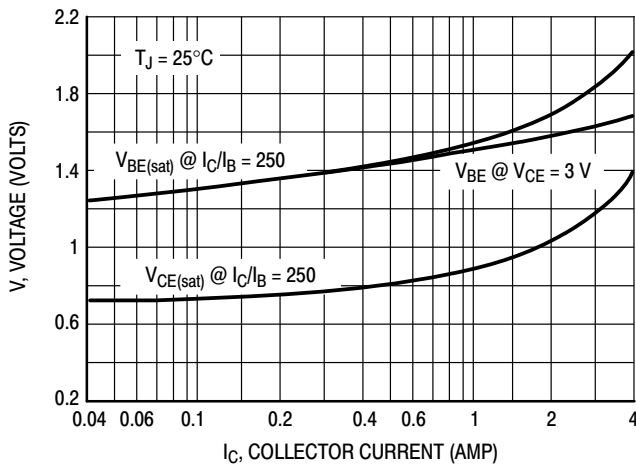


Figure 9. "On Voltages"

MJD112 (NPN), MJD117 (PNP)

NPN MJD112

PNP MJD117

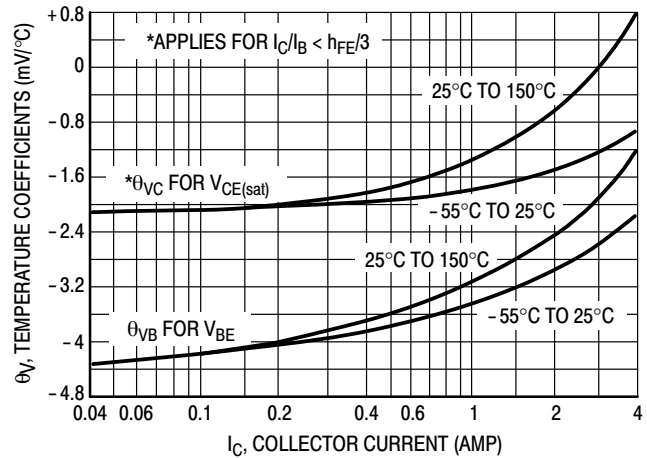
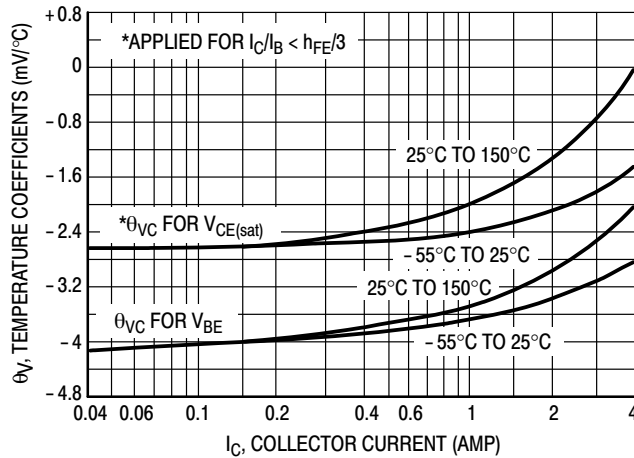


Figure 10. Temperature Coefficients

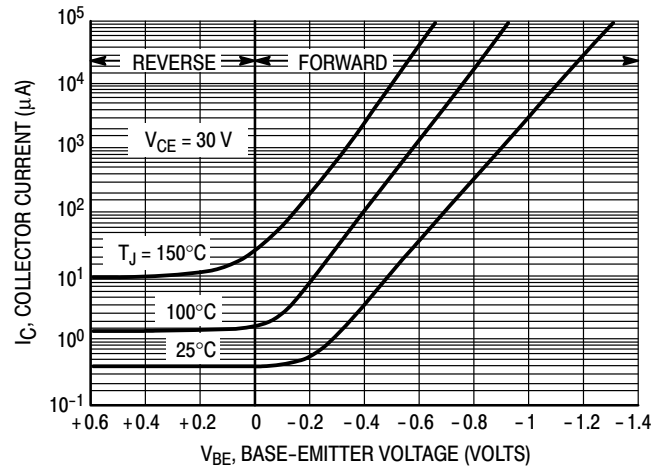
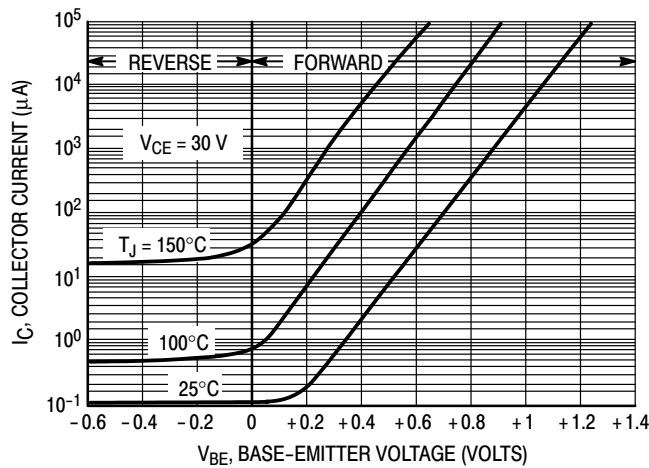


Figure 11. Collector Cut-Off Region

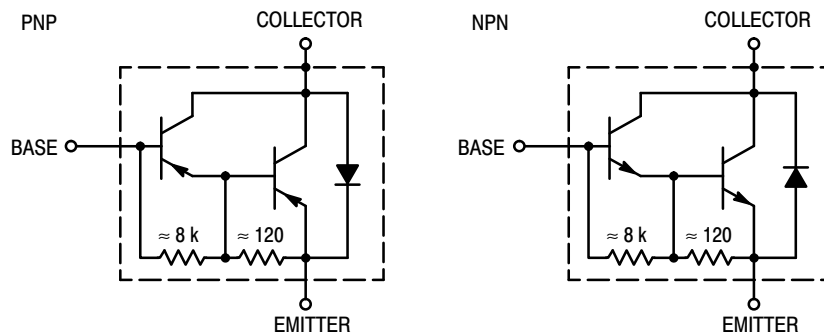


Figure 12. Darlington Schematic

MJD112 (NPN), MJD117 (PNP)

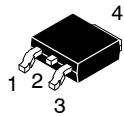
ORDERING INFORMATION

Device	Package Type	Package	Shipping [†]
MJD112G	DPAK (Pb-Free)	369C	75 Units / Rail
NJVMJD112G*	DPAK (Pb-Free)	369C	75 Units / Rail
MJD112-1G	DPAK-3 (Pb-Free)	369D	75 Units / Rail
MJD112RLG	DPAK (Pb-Free)	369C	1,800 Tape & Reel
MJD112T4G	DPAK (Pb-Free)	369C	2,500 Tape & Reel
NJVMJD112T4G*	DPAK (Pb-Free)	369C	2,500 Tape & Reel
MJD117G	DPAK (Pb-Free)	369C	75 Units / Rail
MJD117-1G	DPAK-3 (Pb-Free)	369D	75 Units / Rail
MJD117RLG	DPAK (Pb-Free)	369C	1,800 Tape & Reel
MJD117T4G	DPAK (Pb-Free)	369C	2,500 Tape & Reel
NJVMJD117T4G*	DPAK (Pb-Free)	369C	2,500 Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

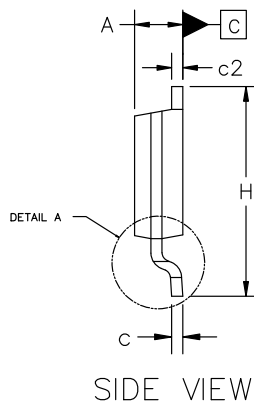
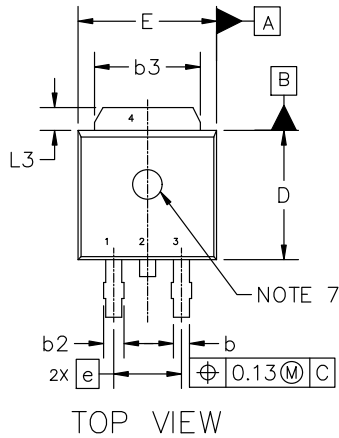




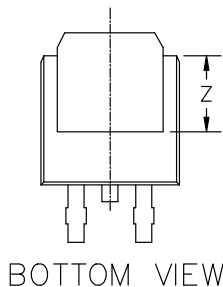
DPAK-3 6.10x6.54x2.28, 2.29P
CASE 369C
ISSUE K

DATE 14 MAY 2026

SCALE 1:1



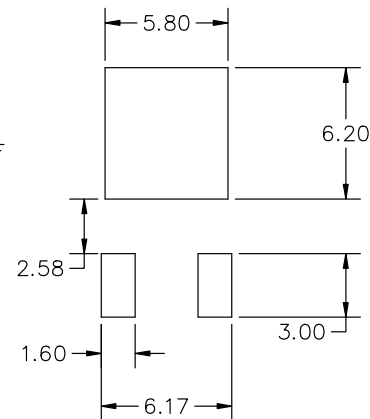
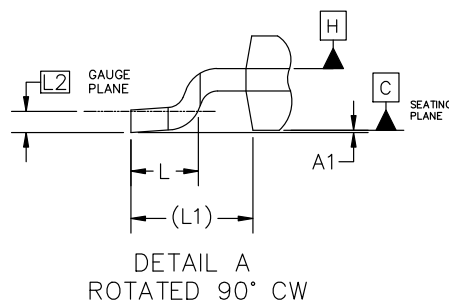
MILLIMETERS			
DIM	MIN	NOM	MAX
A	2.18	2.28	2.38
A1	0.00	---	0.13
b	0.63	0.76	0.89
b2	0.72	0.93	1.14
b3	4.57	5.02	5.46
c	0.46	0.54	0.61
c2	0.46	0.54	0.61
D	5.97	6.10	6.22
E	6.35	6.54	6.73
e	2.29 BSC		
H	9.40	9.91	10.41
L	1.40	1.59	1.78
L1	2.90 REF		
L2	0.51 BSC		
L3	0.89	---	1.27
L4	---	---	1.01
Z	3.93	---	---



ALTERNATE CONSTRUCTIONS

NOTES:

1. DIMENSIONING AND TOLERANCING ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3, AND Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
7. OPTIONAL MOLD FEATURE.



RECOMMENDED MOUNTING FOOTPRINT*

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

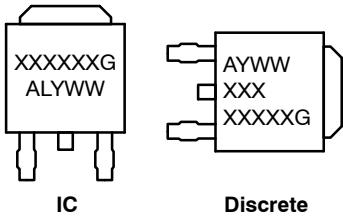
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DESCRIPTION:	DPAK-3 6.10x6.54x2.28, 2.29P	PAGE 1 OF 2

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DPAK–3 6.10x6.54x2.28, 2.29P
 CASE 369C
 ISSUE K

DATE 13 MAY 2026

GENERIC
 MARKING DIAGRAM*



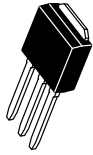
- XXXXXX = Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb–Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR	STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN	STYLE 3: PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE	STYLE 4: PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE	STYLE 5: PIN 1. GATE 2. ANODE 3. CATHODE 4. ANODE
STYLE 6: PIN 1. MT1 2. MT2 3. GATE 4. MT2	STYLE 7: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR	STYLE 8: PIN 1. N/C 2. CATHODE 3. ANODE 4. CATHODE	STYLE 9: PIN 1. ANODE 2. CATHODE 3. RESISTOR ADJUST 4. CATHODE	STYLE 10: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. ANODE

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DESCRIPTION:	DPAK–3 6.10x6.54x2.28, 2.29P	PAGE 2 OF 2

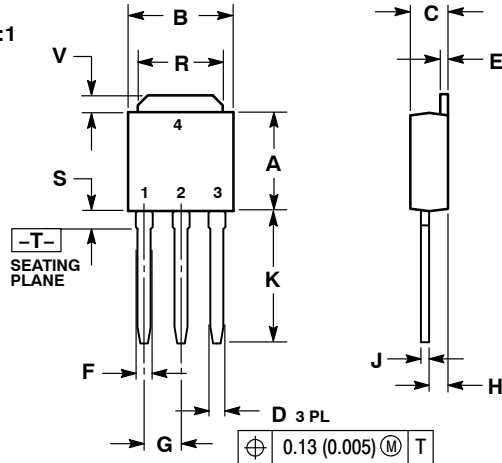
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IPAK
CASE 369D
ISSUE C

DATE 15 DEC 2010

SCALE 1:1

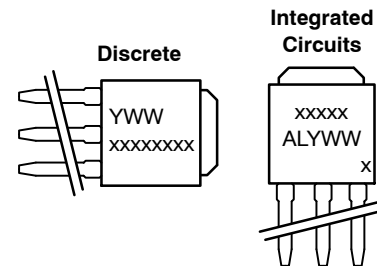


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.235	0.245	5.97	6.35
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.018	0.023	0.46	0.58
F	0.037	0.045	0.94	1.14
G	0.090 BSC		2.29 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.350	0.380	8.89	9.65
R	0.180	0.215	4.45	5.45
S	0.025	0.040	0.63	1.01
V	0.035	0.050	0.89	1.27
Z	0.155	---	3.93	---

GENERIC MARKING
DIAGRAMS

- STYLE 1:
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR
- STYLE 2:
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN
- STYLE 3:
PIN 1. ANODE
2. CATHODE
3. ANODE
4. CATHODE
- STYLE 4:
PIN 1. CATHODE
2. ANODE
3. GATE
4. ANODE
- STYLE 5:
PIN 1. GATE
2. ANODE
3. CATHODE
4. ANODE
- STYLE 6:
PIN 1. MT1
2. MT2
3. GATE
4. MT2
- STYLE 7:
PIN 1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR



xxxxxxxx = Device Code
A = Assembly Location
IL = Wafer Lot
Y = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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